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Titel: MEASURING METHOD FOR POSITION OF ELECTRONIC PARTS

Zusammenfassung

PURPOSE: To eliminate the need for rough positioning by extracting a characteristic pattern corresponding to the characteristic shape of the pin array of an electronic parts from an image obtained by a visual device and measuring the position of the electronic parts on a substrate from the position of the pattern.

CONSTITUTION: A flat package IC10 and the substrate 12 are put in the visual field of the visual device 13 to detect the array of pins 14 of the flat package IC10 and an array of lands 15 of the substrate 12, and straight lines 16, 17, 18, and 19 are found from the pin array or land array to perform the positioning. Then the image of the substrate 12 including the lands 15 is picked up by a camera 26 for the substrate 26 and processed by the image processing part 24 to find the positions of the lands 15 by a robot coordinate system. Then, a hand 25 is moved onto a camera 27 for the IC and pick its image up and the image is processed by the processing part 24 to find the position shift between the IC10 and hand 25 by the robot coordinate system. Lastly, the hand 25 is moved and lowered vertically, thereby mounting the IC10 on the lands 15.

